

Serial No.:

8. (AS NEW HEREIN) A multilayer circuit board comprising a dielectric film
according to claim 6.

REMARKS

This Preliminary Amendment is submitted to delete multiple dependent claims as presented in the concurrently filed subject application. No new matter is presented.

If there are any additional fees associated with filing of this Amendment, please charge the same to our Deposit Account No. 19-3935.

Respectfully submitted,

STAAS & HALSEY LLP

Date: June 28, 2001

By: H. J. Staas
H. J. Staas
Registration No. 22,010

700 Eleventh Street, NW, Suite 500
Washington, D.C. 20001
(202) 434-1500

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VERSION WITH MARKINGS TO SHOW CHANGES MADE

IN THE CLAIMS:

Please AMEND the following claims:

3. (ONCE AMENDED) A dielectric film obtained by heat curing a thermally curable fluorinated o-aminophenol polymer or oligomer according to claim 1 [or 2].

4. (ONCE AMENDED) A process for producing a dielectric film comprising heat curing a thermally curable fluorinated o-aminophenol polymer or oligomer according to claim 1 [or 2].

Please ADD the following claims:

6. (NEW) A dielectric film obtained by heat curing a thermally curable fluorinated o-aminophenol polymer or oligomer according to claim 2.

7. (NEW) A process for producing a dielectric film comprising heat curing a thermally curable fluorinated o-aminophenol polymer or oligomer according to claim 2.

8. (NEW) A multilayer circuit board comprising a dielectric film according to claim 6.

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